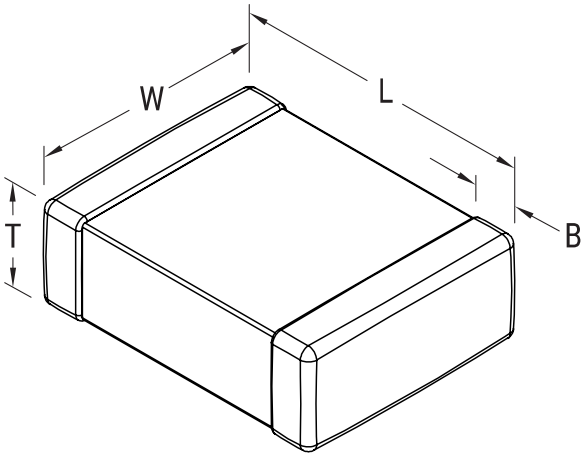
CBR06C239BAGAC

CBR-SMD RF C0G, Ceramic, 2.3 pF, +/-0.1 pF, 250 VDC, C0G, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



Click here for the 3D model.

General Information	
Series	CBR-SMD RF C0G
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
T	0.8mm +/-0.07mm
B	0.4mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	2.3 pF
Tolerance	+/-0.1 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Dissipation Factor	0.224%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	446

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